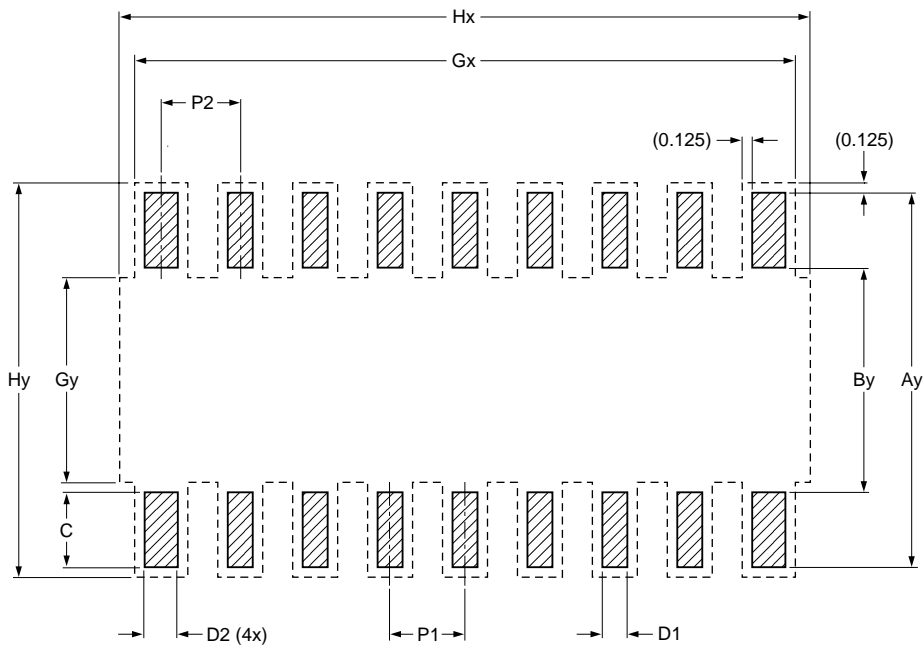


Footprint information for reflow soldering of TSSOP32 package

SOT487-1



Generic footprint pattern  
Refer to the package outline drawing for actual layout

- solder land
- occupied area

**DIMENSIONS in mm**

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.650	0.750	8.900	6.100	1.400	0.400	0.600	10.800	7.000	11.800	9.150